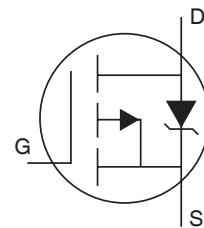


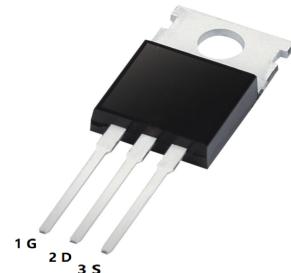
## Description

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



## Features

- $V_{DS}$  (V) = -60V
- $I_D$  = -31A ( $V_{GS}$  = -10V)
- $R_{DS(ON)} < 60m\Omega$  ( $V_{GS}$  = -10V)
- Advanced Process Technology
- Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated Lead-Free



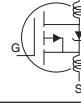
## Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-31	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-22	
$I_{DM}$	Pulsed Drain Current ①	-110	
$P_D @ T_C = 25^\circ C$	Power Dissipation	110	W
	Linear Derating Factor	0.71	W/ $^\circ C$
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy ②	280	mJ
$I_{AR}$	Avalanche Current ①	-16	A
$E_{AR}$	Repetitive Avalanche Energy ①	11	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ ③	-5.0	V/ns
$T_J$	Operating Junction and	$-55$ to $+175$	$^\circ C$
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case )	
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

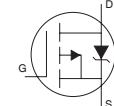
## Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	0.50	1.4	$^\circ C/W$
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface			
$R_{\theta JA}$	Junction-to-Ambient		62	

**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

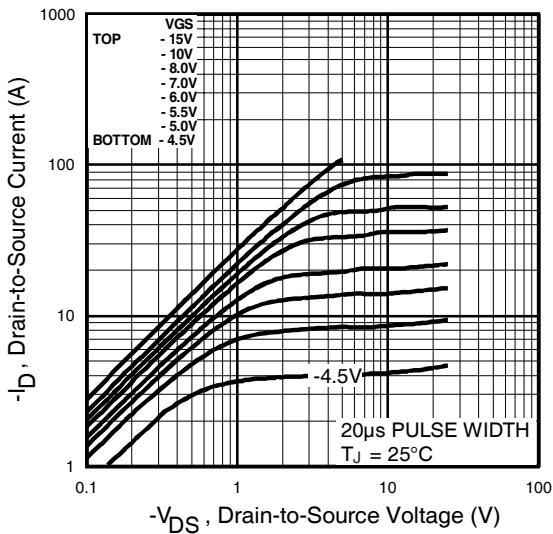
	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	-60			V	$V_{GS} = 0\text{V}$ , $I_D = -250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		-0.034		V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $I_D = -1\text{mA}$
$R_{DS(\text{on})}$	Static Drain-to-Source On-Resistance			60	$\text{m}\Omega$	$V_{GS} = -10\text{V}$ , $I_D = -16\text{A}$ ④
$V_{GS(\text{th})}$	Gate Threshold Voltage	-1.1	-2	-3.0	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu\text{A}$
$g_{fs}$	Forward Transconductance	8.0			S	$V_{DS} = -25\text{V}$ , $I_D = -16\text{A}$
$I_{DSS}$	Drain-to-Source Leakage Current			-25	$\mu\text{A}$	$V_{DS} = -55\text{V}$ , $V_{GS} = 0\text{V}$
				-250		$V_{DS} = -44\text{V}$ , $V_{GS} = 0\text{V}$ , $T_J = 150^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage			100	nA	$V_{GS} = 20\text{V}$
	Gate-to-Source Reverse Leakage			-100		$V_{GS} = -20\text{V}$
$Q_g$	Total Gate Charge			63	nC	$I_D = -16\text{A}$
$Q_{gs}$	Gate-to-Source Charge			13		$V_{DS} = -44\text{V}$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge			29		$V_{GS} = -10\text{V}$ , See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time			14	ns	$V_{DD} = -28\text{V}$
$t_r$	Rise Time			66		$I_D = -16\text{A}$
$t_{d(off)}$	Turn-Off Delay Time			39		$R_G = 6.8\Omega$
$t_f$	Fall Time			63		$R_D = 1.6\Omega$ , See Fig. 10 ④
$L_D$	Internal Drain Inductance		4.5		nH	Between lead, 6mm (0.25in.)
$L_S$	Internal Source Inductance		7.5			from package and center of die contact
$C_{iss}$	Input Capacitance		1200		pF	
$C_{oss}$	Output Capacitance		520			$V_{GS} = 0\text{V}$
$C_{rss}$	Reverse Transfer Capacitance		250			$p\text{F}$ $V_{DS} = -25\text{V}$ $f = 1.0\text{MHz}$ , See Fig. 5

**Source-Drain Ratings and Characteristics**

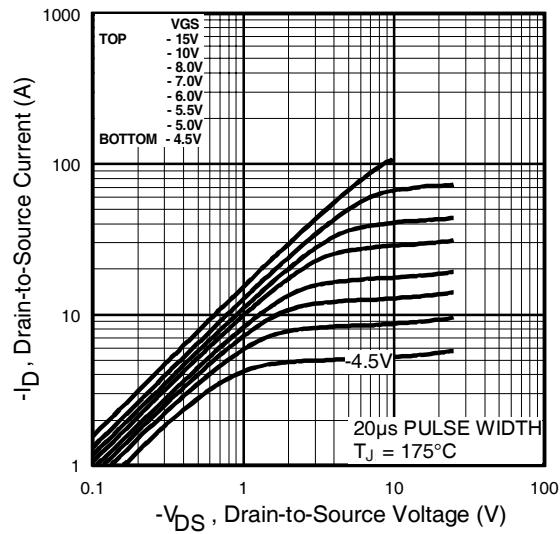
	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)			-31	A	MOSFET symbol showing the integral reverse p-n junction diode.
$I_{SM}$	Pulsed Source Current (Body Diode) ①			-110		
$V_{SD}$	Diode Forward Voltage			-1.3		$T_J = 25^\circ\text{C}$ , $I_S = -16\text{A}$ , $V_{GS} = 0\text{V}$ ④
$t_{rr}$	Reverse Recovery Time		71	110	ns	$T_J = 25^\circ\text{C}$ , $I_F = -16\text{A}$
$Q_{rr}$	Reverse Recovery Charge		170	250	nC	$di/dt = -100\text{A}/\mu\text{s}$ ④

**Notes:**

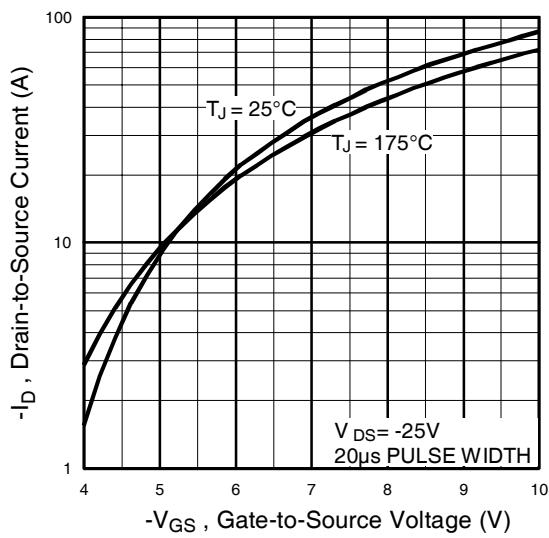
- ① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- ②  $V_{DD} = -25\text{V}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 2.1\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = -16\text{A}$ . (See Figure 12)
- ③  $I_{SD} \leq -16\text{A}$ ,  $di/dt \leq -280\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(\text{BR})\text{DSS}}$ ,  
 $T_J \leq 175^\circ\text{C}$
- ④ Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .



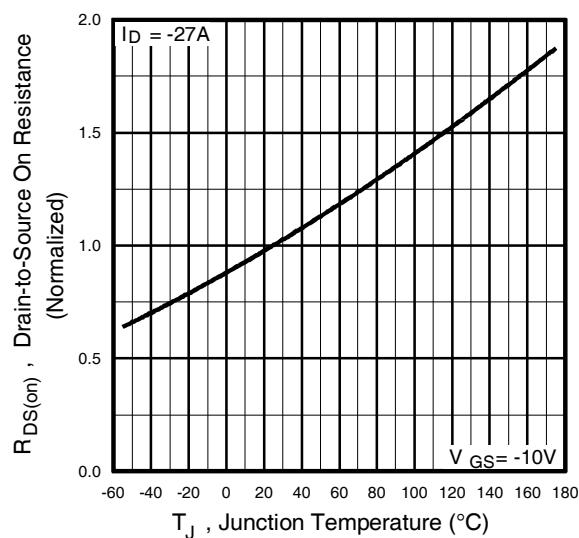
**Fig 1.** Typical Output Characteristics



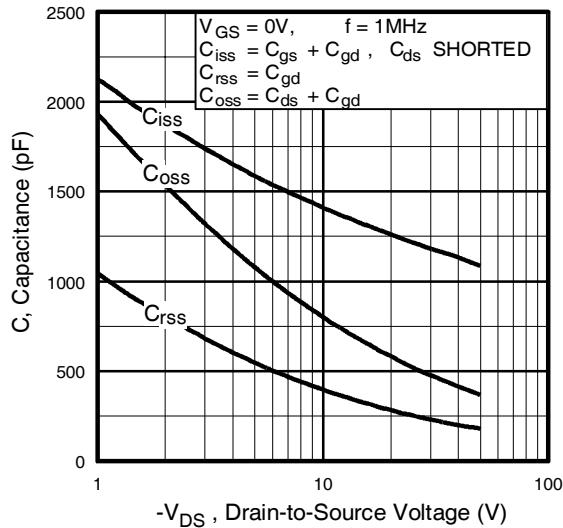
**Fig 2.** Typical Output Characteristics



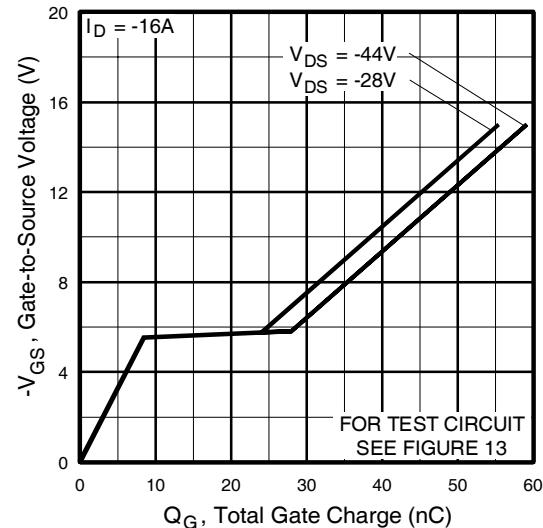
**Fig 3.** Typical Transfer Characteristics



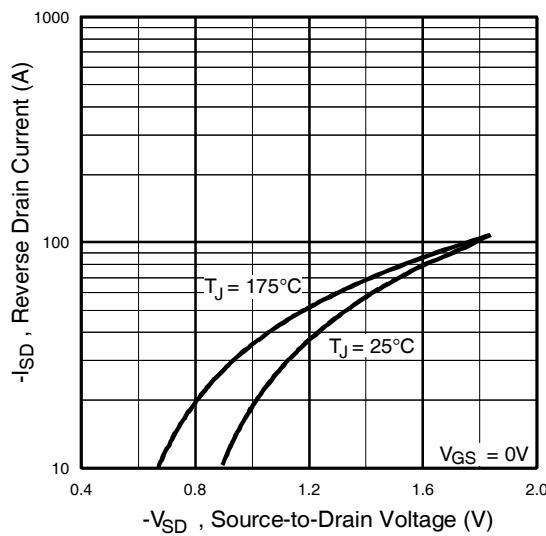
**Fig 4.** Normalized On-Resistance  
Vs. Temperature



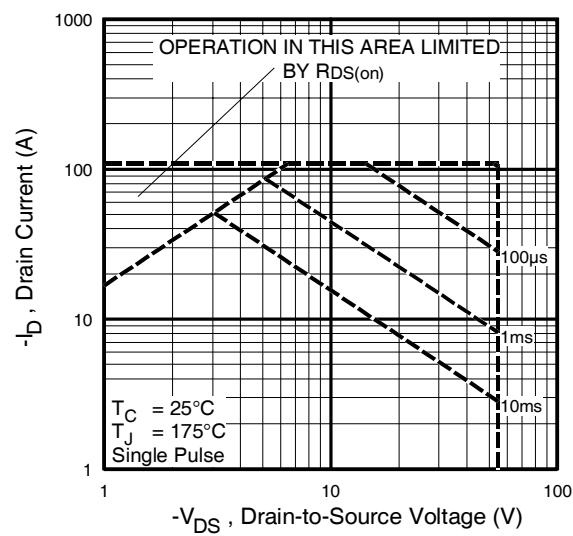
**Fig 5.** Typical Capacitance Vs.  
Drain-to-Source Voltage



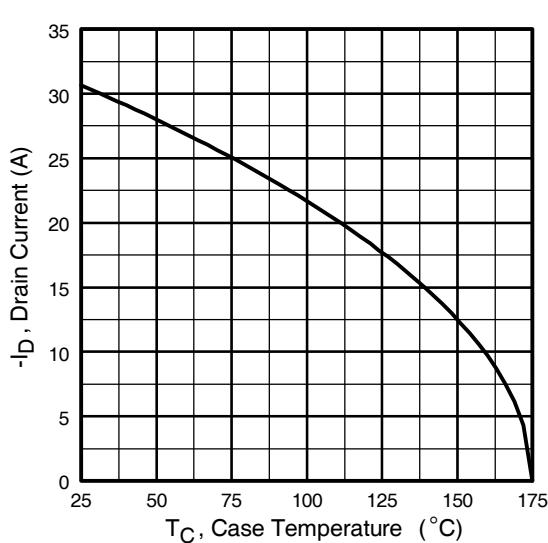
**Fig 6.** Typical Gate Charge Vs.  
Gate-to-Source Voltage



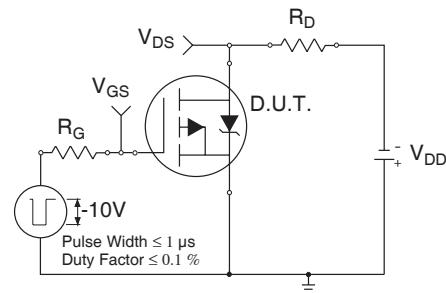
**Fig 7.** Typical Source-Drain Diode  
Forward Voltage



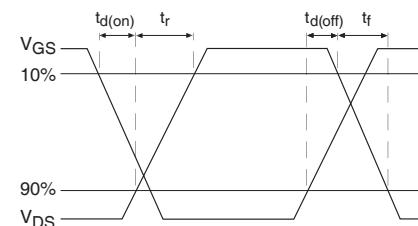
**Fig 8.** Maximum Safe Operating Area



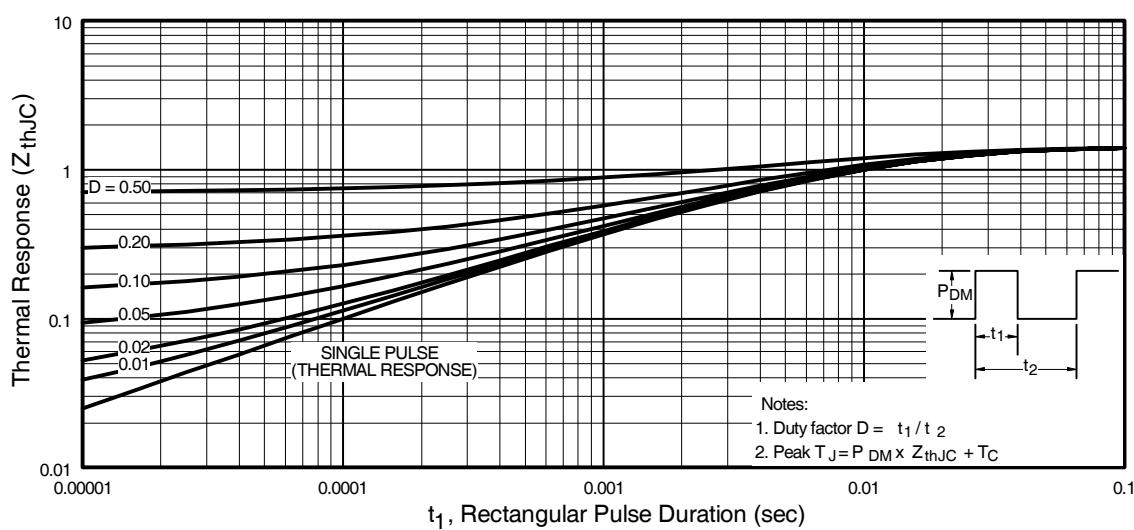
**Fig 9.** Maximum Drain Current Vs. Case Temperature



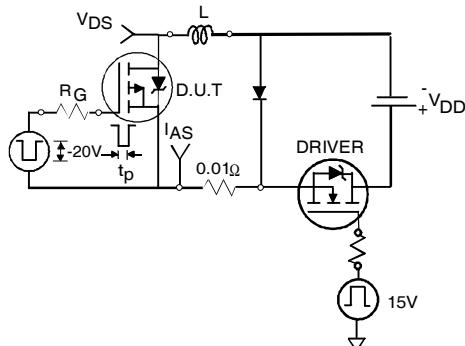
**Fig 10a.** Switching Time Test Circuit



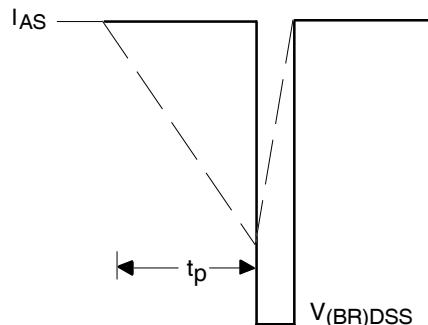
**Fig 10b.** Switching Time Waveforms



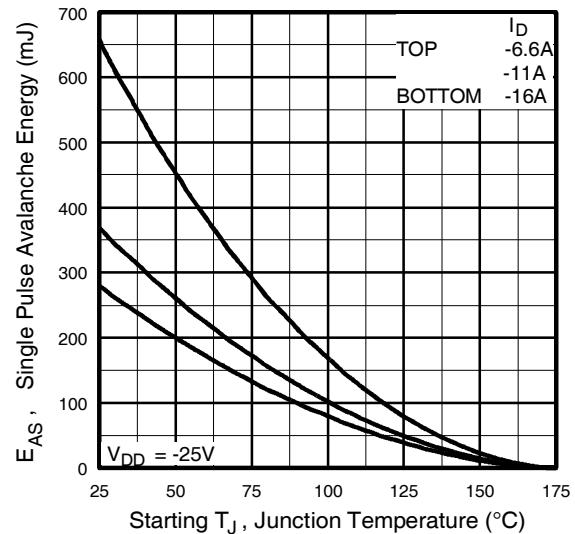
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case



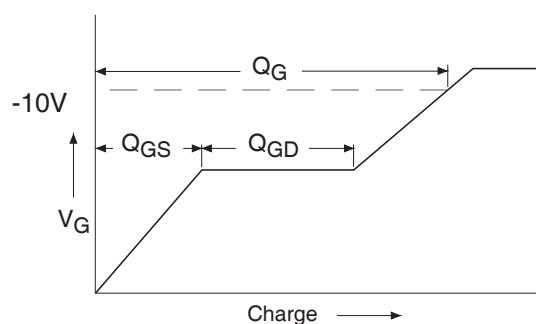
**Fig 12a.** Unclamped Inductive Test Circuit



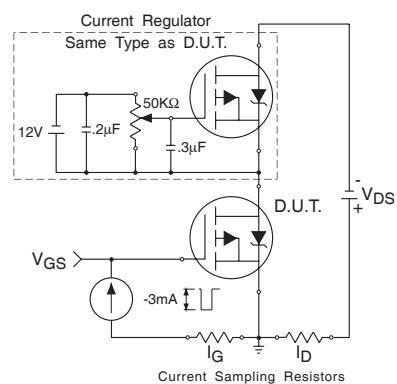
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current

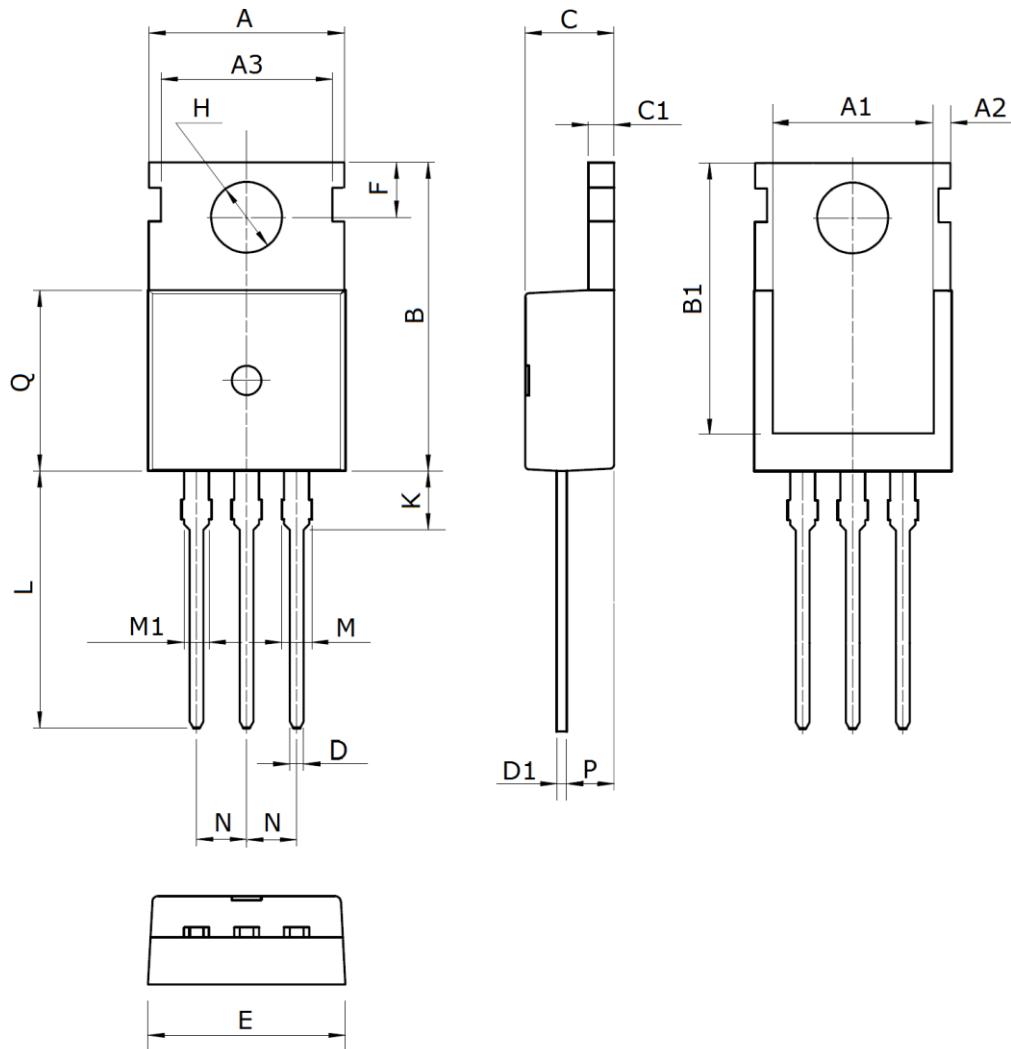


**Fig 13a.** Basic Gate Charge Waveform

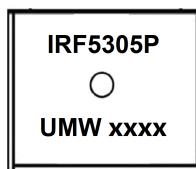


**Fig 13b.** Gate Charge Test Circuit

## Package Mechanical Data TO-220



Symbol	Dimensions (mm)	Symbol	Dimensions (mm)	Symbol	Dimensions (mm)
A	10.0±0.3	C1	1.3±0.2	L	13.2±0.4
A1	8.0±0.2	D	0.8±0.2	M	1.38±0.1
A2	0.94±0.1	D1	0.5±0.1	M1	1.28±0.1
A3	8.7±0.1	E	10.0±0.3	N	2.54(typ)
B	15.6±0.4	F	2.8 ±0.1	P	2.4±0.3
B1	13.2 ±0.2	H	3.6±0.1	Q	9.15±0.25
C	4.5±0.2	K	3.1±0.2		

**Marking****Ordering information**

Order code	Package	Baseqty	Deliverymode
UMW IRF5305PBF	TO-220	1000	Tape and reel

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